



PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of: Jesse Ambrosina, Ali Shajii, and Isao Suzuki

Serial No: 10/032,258

Group Art Unit:

Filing Date: 12/21/2001

Examiner:

Title: APPARATUS AND METHOD FOR THERMAL MANAGEMENT OF A MASS FLOW CONTROLLER

Docket No: 56231-336 (MKS -94)

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Erin Shea

(Person Mailing)

Erin Shea

(Signature)

Assistant Commissioner for Patents
Washington, DC 20231

PRELIMINARY AMENDMENT

Sir:

Please amend the above-identified as follows:

In the Drawings

Please re-label originally submitted "Figure 2" as "Figure 4."

Please re-label originally submitted "Figure 3" as "Figure 6."

Please add the accompanying Figures 2, 3, 5, and 7

REMARKS

On 12/21/2001 the applicant filed three related applications having common inventorship and incorporated each application by reference in every other application. The drawings for the application having serial number 10/032,273 and attorney docket number 56231-334 were inadvertently submitted as the drawings for the present application. However, there is a great deal of commonality among the figures. Those features not included in the inadvertently submitted drawings are supported in the summary, brief description of the drawings, detailed description, claims, and abstract of the present application.

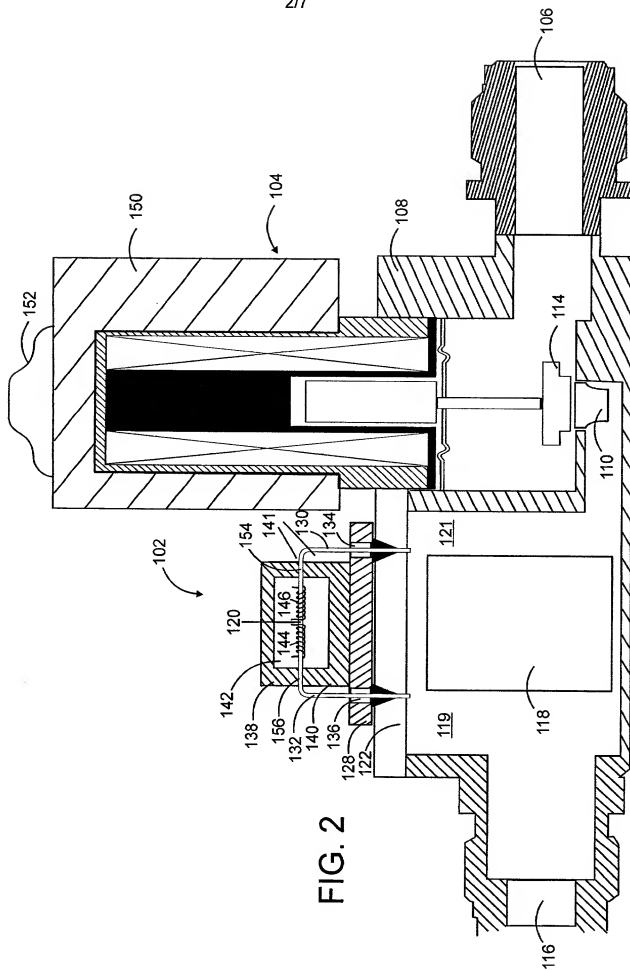
More specifically, "a thermally conductive element", a "thermally conductive enclosure", and an embodiment combining the "thermally conductive element" with "a thermal ground", although not illustrated in the drawings originally submitted with the present application, are described in sufficient detail within the specification to support the requested substitution of drawings. The thermally conductive element illustrated in the enclosed Figures 2 and 5 finds support in the summary at page 5, lines 14-16; the brief description of the drawings at page 6, lines 13-14 and page 14, lines 19-20; the detailed description at page 7, lines 19-22, page 9, lines 25-26 (heatsink 150), and page 10, lines 7 -23; claims 1,3,6,10,16,17,19 and 20; and the abstract.

The combination of thermally conductive element and thermal ground of the enclosed Figure 3 finds support in the brief description of the drawings at page 6, lines 15-20; the detailed description at page 7, lines 19-22 and page 14, lines 19-20; claims 1,3,6,10,16,17,19 and 20; and the abstract.

The thermally conductive enclosure of the enclosed Figure 7 finds support finds support in the summary at page 5, lines 15-20; the detailed description at page 7, lines 4-5, page 14, lines 19-20, and page 15, lines 6-11; and claims 8,18.

The above-referenced descriptive passages provide sufficient support for the elements inadvertently omitted from the originally submitted drawings, which are corrected by the drawings submitted herewith. No new material has been added. The original filing date of December 21, 2001 accorded to the present application is correct.

No additional costs are believed to be due in connection with the filing of this preliminary amendment. However, please charge any necessary fees to Deposit Account No. 50-1133.



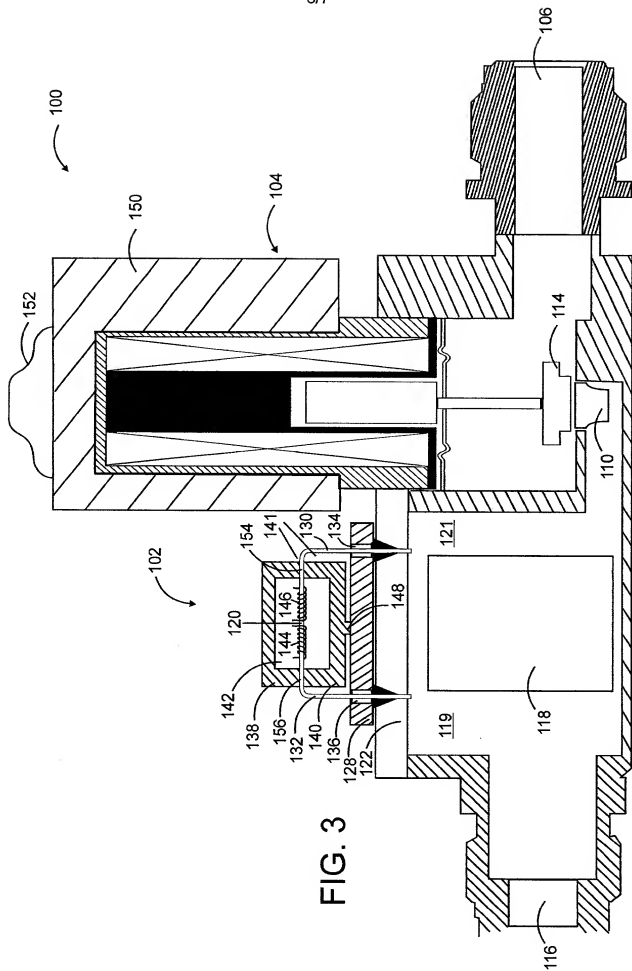


FIG. 3

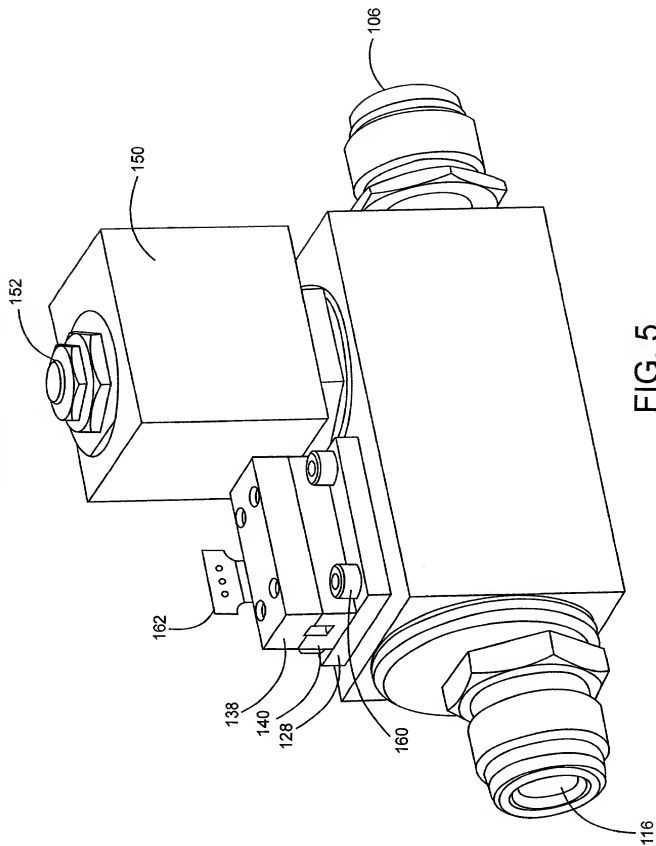


FIG. 5

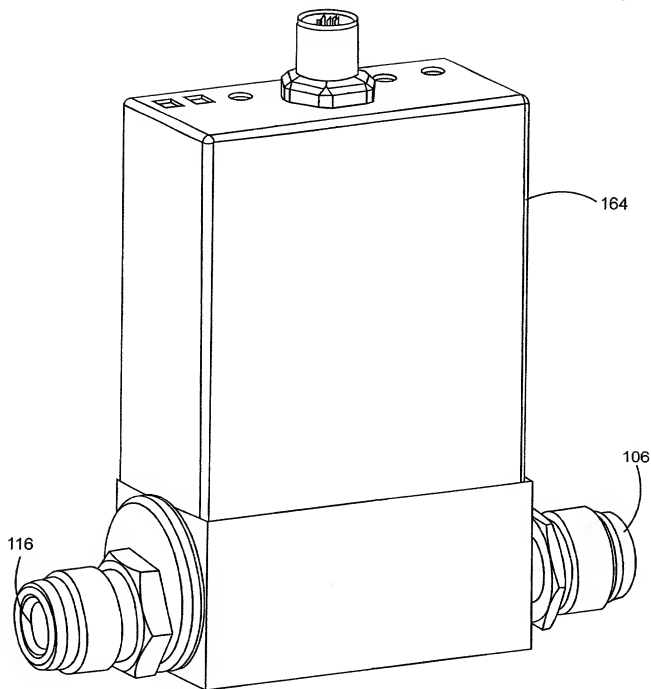


FIG. 7